WHAT IS CLAIMED IS:

1. A fluid ejector cartridge, comprising:

a manifold that is molded from a polymer that includes at least one thermally conductive filler material; and

a fluid ejector die module attached to the manifold.

2. The fluid ejector cartridge of claim 1, wherein the manifold and fluid ejector die are made of materials having similar coefficients of thermal expansion.

3. The fluid ejector cartridge of claim 1, wherein the at least one thermally conductive filler material has a thermal conductivity greater than about 10 W/m°C.

4. The fluid ejector cartridge of claim 1, wherein the at least one thermally conductive filler material has a thermal conductivity less than about 100 W/m°C.

5. The fluid ejector cartridge of claim 4, wherein the at least one thermally conductive filler material has a thermal conductivity of about 10 W/m°C to about 100 W/m°C.

6. The fluid ejector cartridge of claim 1, wherein the at least one thermally conductive filler material is a graphite material.

7. The fluid ejector cartridge of claim 6, wherein the graphite material is formed using a petroleum pitch base material.

8. The fluid ejector cartridge of claim 1, wherein the at least one thermally conductive filler material is a ceramic material.

9. The fluid ejector cartridge of claim 8, wherein the at least one ceramic material is at least one of boron nitride and aluminum nitride.

10. The fluid ejector cartridge of claim 1, wherein the polymer is at least one of liquid crystal polymer, polyphenylene sulfide and polysulfone.

11. The fluid ejector cartridge of claim 1, wherein the polymer used to form the manifold is chemically resistant to ink.

12. The fluid ejector cartridge of claim 1, further including a container, wherein the manifold and container are integrally molded as a single piece.

13. The fluid ejector cartridge of claim 1, wherein the at least one thermally conductive filler material is oriented substantially parallel to an oriented flow area of the fluid ejector die module.

14. A method of manufacturing a fluid ejector cartridge, comprising:

at least partially molding a manifold using a polymer that includes at least one thermally conductive filler material; and

attaching the manifold to a fluid ejector die.

15. The method of claim 14, wherein at least partially molding the manifold comprises completely molding the manifold from the polymer that includes the at least one thermally conductive filler material.

16. The method of claim 14, further comprising mixing at least one filler material having a thermal conductivity greater than about 10 W/m°C into the polymer to form the polymer that includes the at least one thermally conductive filler material.

17. The method of claim 14, further comprising mixing at least one filler material having a thermal conductivity less than about 100 W/m°C into the polymer to form the polymer that includes the at least one thermally conductive filler material.

18. The method of claim 17, wherein mixing at least one filler material comprises mixing in a filler material that has a thermal conductivity of about 10 W/m°C to about 100 W/m°C.

19. The method of claim 14, wherein at least partially molding the manifold comprises orienting the at least one filler material substantially parallel to an oriented flow area of the fluid ejector die.